

SMCJ-HRA Series





Description

The SMCJ-HRA High Reliability series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events. These are available with a variety of upscreening options for enhanced reliability.

Agency Approvals

Agency	Agency File Number
<i>71</i> °	E230531

Maximum Ratings and Thermal Characteristics (T_{Δ} =25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation at T_A =25°C by 10/1000 μ s waveform (Fig.1)(Note 1), (Note 2)	P _{PPM}	1500	W
Power Dissipation on infinite heat sink at T _A =50°C	P _{M(AV)}	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 3)	I _{FSM}	200	А
Maximum Instantaneous Forward Voltage at 100A for Unidirectional only (Note 4)	V _F	3.5/5.0	V
Operating Junction and Storage Temperature Range	$T_{J},\;T_{STG}$	-65 to 150	°C
Typical Thermal Resistance Junction to Lead	R _{uJL}	15	°C/W
Typical Thermal Resistance Junction to Ambient	R _{uJA}	75	°C/W

Notes:

- 1. Non-repetitive current pulse, per Fig. 3 and derated above $T_A = 25^{\circ}\text{C}$ per Fig. 2.
- 2. Mounted on copper pad area of 0.31x0.31" (8.0 x 8.0mm) to each terminal.
- 3. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cycle=4 per minute maximum.
- **4.** VF<3.5V for VBR \leq 200V and VF<5.0V for VBR \geq 201V.

Features

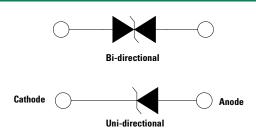
- High reliability devices with fabrication and assembly lots traceability
- Enhanced reliability screening options are available in reference to MIL-PRF-19500. Refer to screen process table for more detail on screening options
- For surface mounted applications to optimize board space
- Low profile package
- Built-in strain relief
- $V_{BR} @T_J = V_{BR} @25^{\circ}C \times (1+\alpha T \times (T_J 25))$

(αT:Temperature Coefficient)

- Glass passivated chip junction
- 1500W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycles):0.01%
- Fast response time: typically less than 1.0ps from 0V to BV min

- Excellent clamping capability
- Low incremental surge resistance
- Typical I_R less than 1μA above 12V
- High Temperature soldering guaranteed: 260°C/40 seconds at terminals
- Plastic package has Underwriters laboratory flammability 94V-O
- Meet MSL level1, per J-STD-020, LF maximun peak of 260°C
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- 2nd level interconnect is Pb-free per IPC/JEDEC J-STD-609A.01
- Recognized to UL 497B as an Isolated Loop Circuit Protector

Functional Diagram



Applications

SMCJ-HRA devices are ideal for the high reliability protection of I/O Interfaces, $V_{\rm cc}$ bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.



Electrical Characteristics

SMCJ5.0A-HRA SMCJ5.0CA-HRA GDEH BDEH 5.0 6.40 7.00 10 9.2 163.0 80 SMCJ6.0A-HRA SMCJ6.0CA-HRA GDGH BDGH 6.0 6.67 7.37 10 10.3 145.7 80 SMCJ6.5A-HRA SMCJ6.5CA-HRA GDKH BDKH 6.5 7.22 7.98 10 11.2 134.0 50 SMCJ7.0A-HRA SMCJ7.0CA-HRA GDMH BDMH 7.0 7.78 8.60 10 12.0 125.0 20 SMCJ7.5A-HRA SMCJ7.5CA-HRA GDPH BDPH 7.5 8.33 9.21 1 12.9 116.3 10 SMCJ8.0A-HRA SMCJ8.0CA-HRA GDRH BDRH 8.0 8.89 9.83 1 13.6 110.3 5	V _R
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SMCJ9.0A-HRA SMCJ9.0CA-HRA GDVH BDVH 9.0 10.00 11.10 1 15.4 97.4 1	0 X
SMCJ10A-HRA SMCJ10CA-HRA GDXH BDXH 10.0 11.10 12.30 1 17.0 88.3	5 X
SMCJ11A-HRA SMCJ11CA-HRA GDZH BDZH 11.0 12.20 13.50 1 18.2 82.5	1 X
SMCJ12A-HRA SMCJ12CA-HRA GEEH BEEH 12.0 13.30 14.70 1 19.9 75.4	1 X
SMCJ13A-HRA SMCJ13CA-HRA GEGH BEGH 13.0 14.40 15.90 1 21.5 69.8	1 X
SMCJ14A-HRA SMCJ14CA-HRA GEKH BEKH 14.0 15.60 17.20 1 23.2 64.7	1 X
SMCJ15A-HRA SMCJ15CA-HRA GEMH BEMH 15.0 16.70 18.50 1 24.4 61.5	1 X
	1 X
SMCJ17A-HRA SMCJ17CA-HRA GERH BERH 17.0 18.90 20.90 1 27.6 54.4	1 X
SMCJ18A-HRA SMCJ18CA-HRA GETH BETH 18.0 20.00 22.10 1 29.2 51.4	1 X
SMCJ20A-HRA SMCJ20CA-HRA GEVH BEVH 20.0 22.20 24.50 1 32.4 46.3	1 X
	1 X
SMCJ24A-HRA SMCJ24CA-HRA GEZH BEZH 24.0 26.70 29.50 1 38.9 38.6	1 X
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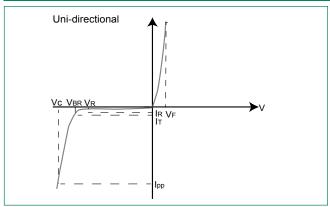
Note:1.SMCJ-HRA voltage binning can be specified by customer's request via contacting Littlefuse service

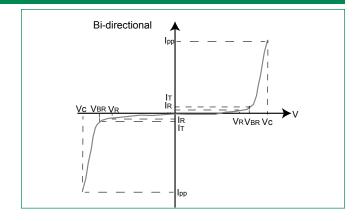


Screen Process	
100% vision inspection	MIL-STD-750 method 2074
100%High Temperature Storage Life (168hrs,150C)	MIL-STD-750 method 1031
100% X-RAY inspection	MIL-STD-750 method 2076
100% Temperature cycle test (-55-150C, 20 cycles, dwell time 15 min)	MIL-STD-750 method 1051
100% Reflow (2X)	JEDEC J-STD-020
100% surge test (2x)	MIL-STD-750 method 4066
100% HTRB(150C, Bias=VR(80% breakdown voltage), 96hrs), for Bi-direction products, 96hrs for each direction	MIL-STD-750 method 1038
Final electrical test(100% 3 sigma limit, 100% dynamic test and PAT limit)	MIL-STD-750 method 4016.4021.4011

Note: Up-screen program can be specified by customer's request via contacting Littlefuse service

I-V Curve Characteristics





 $\textbf{P}_{\textbf{PPM}} \ \ \textbf{Peak Pulse Power Dissipation} - \text{Max power dissipation}$

- V_R Stand-off Voltage Maximum voltage that can be applied to the TVS without operation
- V_{BR} Breakdown Voltage Maximum voltagethat flows though the TVS at a specified test current (I_T)
- Vc Clamping Voltage Peak voltage measured across the suppressor at a specified lppm (peak impulse current)
- $\textbf{I}_{\textbf{R}} \qquad \textbf{Reverse Leakage Current} \textbf{Current measured at V}_{\textbf{R}}$
- V_F Forward Voltage Drop for Uni-directional

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Figure 1 - TVS Transients Clamping Waveform

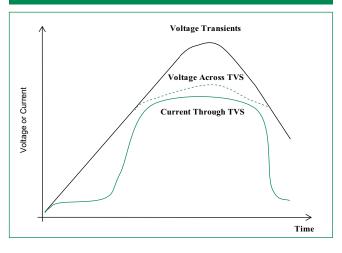
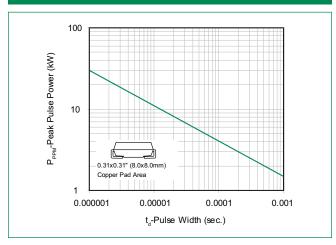


Figure 2 - Peak Pulse Power Rating





Ratings and Characteristic Curves (T_A=25°C unless otherwise noted) (Continued)

Figure 3 - Pulse Derating Curve

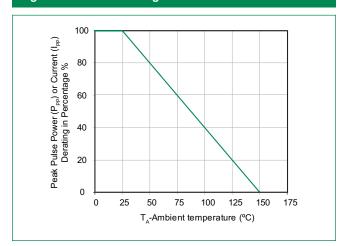


Figure 4 - Pulse Waveform

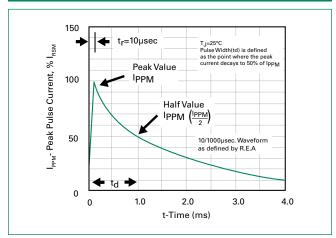


Figure 5 - Typical Junction Capacitance

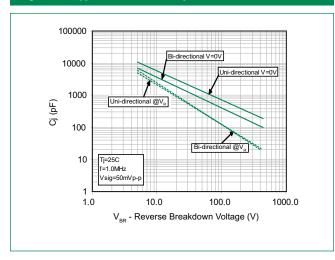


Figure 6 - Steady State Power Dissipation Derating Curve

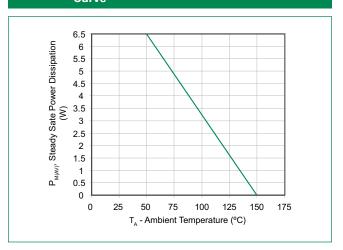
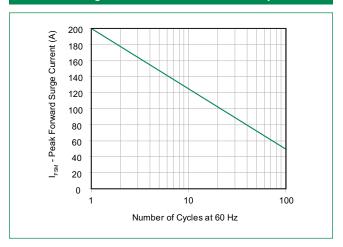


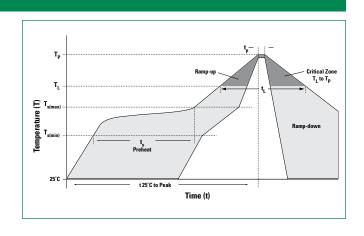
Figure 7 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional Only





Soldering Parameters

Reflow Condition		Lead-free assembly
Pre Heat	-Temperature Min (T _{s(min)})	150°C
	-Temperature Max (T _{s(max)})	200°C
	-Time (min to max) (t _s)	60 – 180 secs
Average ram	3°C/second max	
T _{S(max)} to T _L - Ramp-up Rate		3°C/second max
Reflow	-Temperature (T _L) (Liquidus)	217°C
	-Time (min to max) (t _s)	60 - 150 seconds
Peak Temperature (T _P)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t _p)		20 - 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T _p)		8 minutes Max.
Do not exceed		280°C



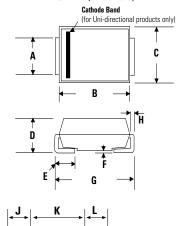
Physical Specifications

Weight	0.007 ounce, 0.21 grams
Case	JEDEC DO214AB. Molded plastic body over glass passivated junction
Polarity	Color band denotes positive end (cathode) except Bidirectional
Terminal	Matte Tin-plated leads, Solderable per JESD22-B102

Environmental Specifications

High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Thermal Shock	JESD22-A106
MSL JEDEC-J-STD-020, Level 1	
H3TRB JESD22-A101	
RSH	JESD22-B106

Dimensions

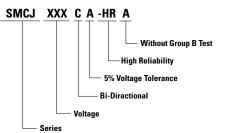


DO-214AB (SMC J-Bend)

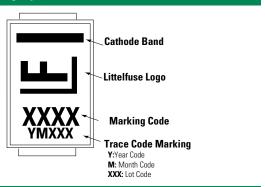
Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
Α	0.114	0.126	2.900	3.200
В	0.260	0.280	6.600	7.110
С	0.220	0.245	5.590	6.220
D	0.079	0.103	2.060	2.620
E	0.030	0.060	0.760	1.520
F	0.002	0.008	0.051	0.203
G	0.305	0.320	7.750	8.130
Н	0.006	0.012	0.152	0.305
I	0.129	-	3.300	-
J	0.094	-	2.400	-
K	-	0.165	-	4.200
L	0.094	-	2.400	-



Part Numbering System SMCJ XXX C A



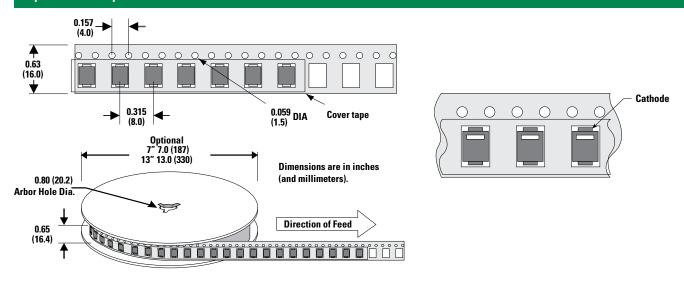
Part Marking System



Packaging

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
SMCJxxxXX-HRA	DO-214AB	3000	Tape & Reel – 16mm tape /13" reel	EIA STD RS-481
SMCJxxxXX-HRAT7	DO-214AB	500	Tape & Reel – 16mm tape /7" reel	EIA STD RS-481

Tape and Reel Specification



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